2SJ0364G

Silicon P-channel junction FET

For analog switch circuits

■ Features

- Low ON resistance
- Low-noise characteristics

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Gate-drain surrender voltage	V _{GDS}	65	V	
Drain current	I_D	-20	mA	
Gate current	I_G	-10	mA	
Power dissipation	P_{D}	150	mW	
Channel temperature	T _{ch}	150	°C	
Storage temperature	T_{stg}	-55 to +150	°C	

Package

- Code
 - SMini3-F2
- Pin Name
 - 1: Source
- 2: Drain
- 3: Gate
- Marking Symbol: 4M

■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

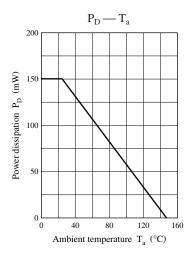
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Gate-drain surrender voltage	V _{GDS}	$I_G = 10 \mu\text{A}, V_{DS} = 0$	65	0,		V
Drain-source current *	I_{DSS}	$V_{DS} = -10 \text{ V}, V_{GS} = 0$	- 0.6	0	-6.0	mA
Gate-source cutoff current	I_{GSS}	$V_{GS} = 30 \text{ V}, V_{DS} = 0$	1.90		10	nA
Gate-source cutoff voltage	V _{GSC}	$V_{DS} = -10 \text{ V}, I_{D} = -10 \mu\text{A}$		1.5	3.5	V
Forward transfer admittance	Y _{fs}	$V_{DS} = -10 \text{ V}, I_D = -1 \text{ mA}, f = 1 \text{ kHz}$	1.8	2.5		mS
Short-circuit forward transfer capacitance (Common source)	C _{iss}	$V_{DS} = -10 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$		12		pF
Reverse transfer capacitance (Common source)	C _{rss}	28 110 :		4		pF
Drain-source ON resistance	R _{DS(on)}	$V_{DS} = -10 \text{ mV}, V_{GS} = 0$		300		Ω

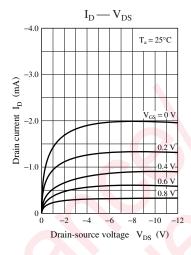
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

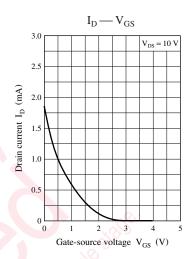
- 2. Observe precautions for handling. Electrostatic sensitive devices.
- 3. *: Rank classification

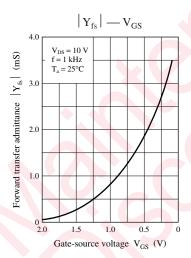
Rank	Р	Q	R
I _{DSS} (mA)	− 0.6 to −1.5	-1.0 to -3.0	-2.5 to -6.0

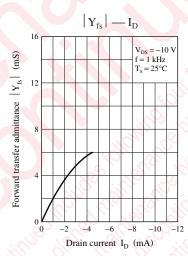
Note) The part number in the parenthesis shows conventional part number.

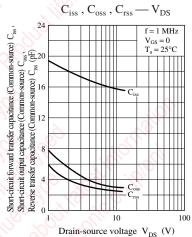






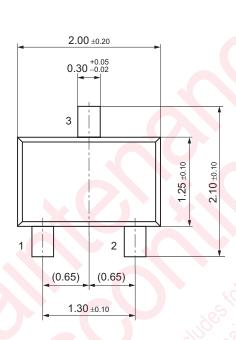


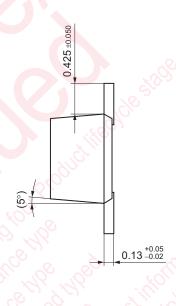


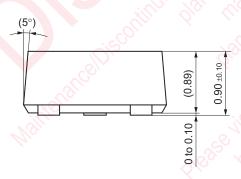


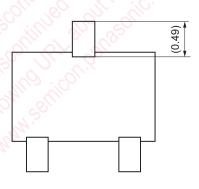
2 SJF00054CED

SMini3-F2 Unit: mm









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